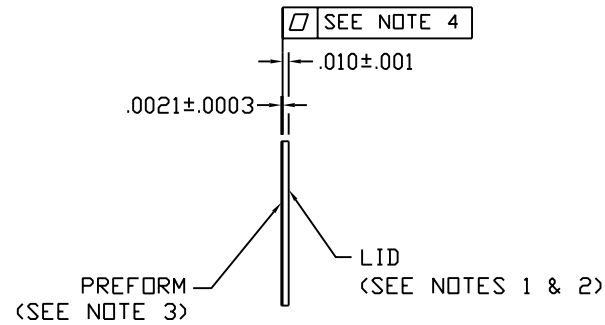
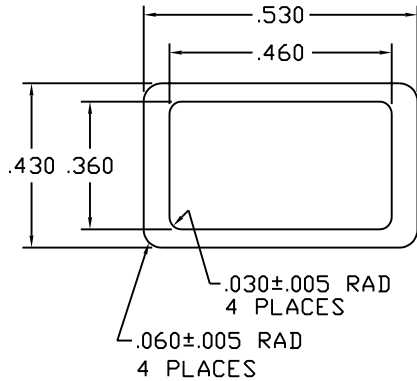


SSM P/N CL534302



NOTES

1. MAT'L : KOVAR OR ALLOY 42
2. PLATING : 1st LAYER 50/350 MICROINCHES Ni
2nd LAYER Au
3rd LAYER 50/350 MICROINCHES Ni
4th LAYER 25 MICROINCHES MINIMUM Au

NOTES : TOTAL NICKEL LAYERS SHALL NOT EXCEED 450 MICROINCHES AND THE SUM OF BOTH GOLD LAYERS SHALL BE 50 MICROINCHES MINIMUM.

3. PREFORM - 80% ± 1% Au
20% Sn
4. FLATNESS : ONE MIL (.001) MAXIMUM PER 1/2" T.I.R
5. TOLERANCES TO BE (XXX) 3 PLACES ±.003 UNLESS OTHERWISE NOTED

DESIGN	BW	08/03 89	DESCRIPTION Hi-Rel Combo Lid	
APPRD	VG	03/08 00	PART NAME CL534302	SCALE 4 = 1 DEPT
Spectrum Semiconductor Materials, Inc. 2027 O'Toole Ave San Jose, CA 95131 PH: (408) 435-5555 Fx: (408)435-8226			MFG: Williams Advanced Materials, Inc. PART No. HRC-2007	

